

Electronic Acknowledgement Receipt

EFS ID:	1196400
Application Number:	10618113
Confirmation Number:	8697
Title of Invention:	Wafer-level chip scale package and method for fabricating and using the same
First Named Inventor:	Rajeev Joshi
Customer Number:	27966
Filer:	kenneth E. Horton/Erin Cowles
Filer Authorized By:	kenneth E. Horton
Attorney Docket Number:	11948.21
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1	Amendment - After Non-Final Rejection	4OAresponsefiled.pdf	769736	no	8

Warnings:	
Information:	
Total Files Size (in bytes):	769736
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